COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

<table>
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<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: TIDA-00792</th>
<th>REV: E2</th>
<th>SUN REV: Not In VersionControl</th>
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<td>TID #: TIDA-00792</td>
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| PLOT NAME = Bottom Assembly Drawing | GENERATED: 3/15/2017 12:19:40 PM | TEXAS INSTRUMENTS |
|------------------------------------|---------------------------------|-----------------*
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